INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)	ATTY. DOCKET NO. 7720/FPS/MMCS/APC	SERIAL NO. 10/632,107
	APPLICANT Alexander T. SCHWARM et al.	
	FILING DATE August 1, 2003	GROUP 2812

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow		
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes		
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions		
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium		
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure	—	
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles		
	09/998,372	11/30/01	Paik	Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to Improve Pad Life		
	09/998,384	11/30/01	Paik	Feedforward and Feedback Control for Conditioning of Chemical Mechanical Polishing Pad		
EXAMINER				DATE CONSIDERED		

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements		
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control		
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing		
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities		
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control		
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes		
	10/174,377	06/18/02	Schwarm et al.	Feedback Control of Sub-Atmospheric Chemical Vapor Deposition Processes		
	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data		
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control		

EXAMINER	DATE CONSIDERED

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